LISTING OF CLAIMS

Claims 1-10. (Canceled)

Claim 11. (New) A method of producing light-conducting LED bodies of a material that is free-flowing before the final solidification comprising the steps of:

providing a mold having a floor region and a charging point, one or more individual LED bodies each having at least one-light emitting chip and at least two electrodes connected electrically with said chip;

injecting free-flowing material between said floor region of said mold and said chip at least approximately parallel to said chip plane and at least approximately normal to a plane formed by said two electrodes;

choking by at least a cross-sectional constriction said free-flowing material above said charging and below said chip plane on the mold side of said charging point when a first distance measured by volumetric flow between said electrode plane and said charging point is greater than 35% of a second distance measured by the volumetric flow between said charging point and said mold side of said mold situation opposite said charging point; and

choking on said mold side opposite said charging point when said first distance is smaller than or equal to said second distance.

Claim 12. (New) The method according to claim 11 wherein said cross-sectional constriction is produced by a projection of said mold projecting into a cavity of said mold.

Claim 13. (New) The method according to claim 12 wherein said projection is part of a slide which is moved into the cavity of said mold and supports injecting said free-flowing material.

Claim 14. (New) The method of claim 13 further comprising the step of:

moving said slide at least partially back to or behind an outer contour of a luminescent diode of said LED wherein the movement of said slide reduces said volumetric flow of said pre-flowing material and makes a facial surface of said mold turn toward a center line of said LED.

Claim 15. (New) The method according to claim 13 wherein said slide is pushed in before said step of injection said free-flowing material and is continuously moved back during charging, over the entire injecting operation.

Claim 16. (New) The method of claim 12 wherein said cross-sectional constriction is produced by said projection projecting wedge-like into said mold.

Claim 17. (New) The method of claim 12 wherein a contour of a spatial surface of said mold is turned toward the LED center line enclosing an angle of 5 to 45 degrees with the LED center line, while the point of interception between the prolongation of said contour and said LED center line lies above said chip plane.

Claim 18. (New) The method of claim 12 wherein said cross-sectional constriction is produced by a crescent or circular arc projection.

Claim 19. (New) The method claim 12 wherein a spatial surface of the molding element is turned toward the LED center line is a surface part of the outer contour of a luminescent diode of said LED.

Claim 20. (New) The method according to claim 12 wherein the point of the upper edge of said molding element that comes nearest to the LED center line lies on or below said chip plane.